

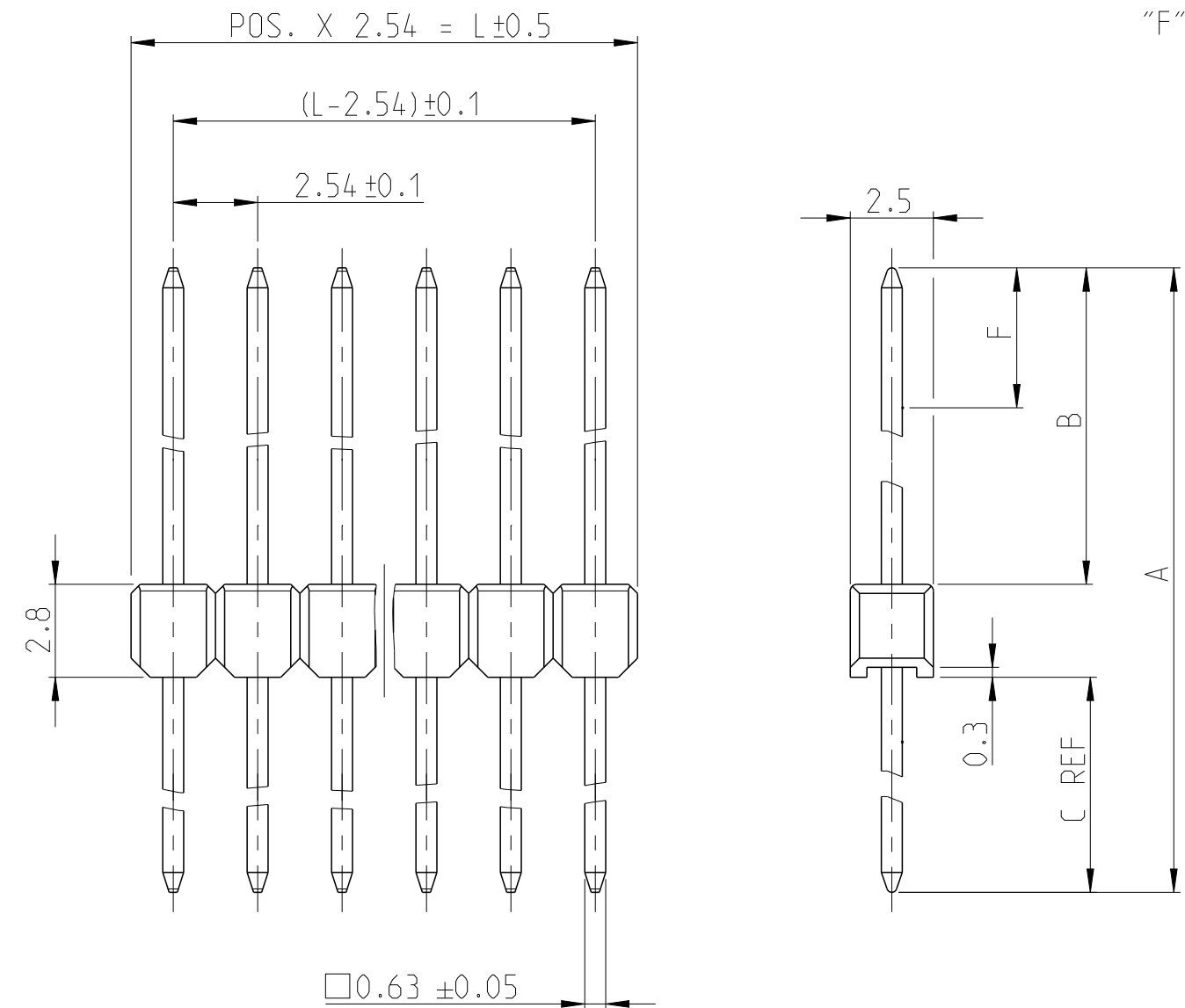
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P	LTR	DESCRIPTION			DATE	DWN	APVD		
	AC1	TOLERANCE ADDED FOR DIMENSION 0.63			17 JUN2019	SS	PS		
	AC2	NOTE 1 0.76 µm PLATING UPDATE (PdNi+AuFLASH)			10 JUL2023	BGC	PS		

D

C

B

A



CONTACT PIN	CuZn	SEE TABLE
PIN HOUSING	PBT GV	SEE TABLE
DESCRIPTION	MATERIAL	FABRE/COLOR/PLATING/SURFACE

NOTES:

1 MATING SIDE : AREA "F" MIN 0.76 µm (PdNi + Au FLASH) 1.27 µm NICKEL BY AREA "B"
(Alternative plating - Min 0.76 µm Au OVER 1.27 µm Ni)
SOLDER SIDE: MIN 3 µm TIN OVER 1.27 µm NICKEL

2 MATING AND SOLDER SIDE : MIN 3 µm TIN OVER 1.27 µm NICKEL

3 MATING SIDE: AREA "F" 0.13 µm GOLD OVER 1.27 µm NICKEL
BY AREA "B"
SOLDER SIDE: MIN 3 µm TIN OVER 1.27 µm NICKEL

4 COLOR OF HOUSING: GREY

5 COLOR OF HOUSING: GREEN

6 TOLERANCES NOT CUMULATIVE

7 THE NUMBER OF POSITION PER ROW HAS TO BE ADDED TO THE BASE NO. AS A DASH NO.
EG: 2-826629-0 = 20 POSITIONS

THE NUMBER OF POSITIONS PER ROW IS ALSO THE FACTOR FOR THE WEIGHT DETERMINATION
E.G: 20 X 0.0654 g = 1.308 g

8 OBSOLETE

SCALE 8:1
LAYOUT FOR HOLES ON PCB

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REVISIONS

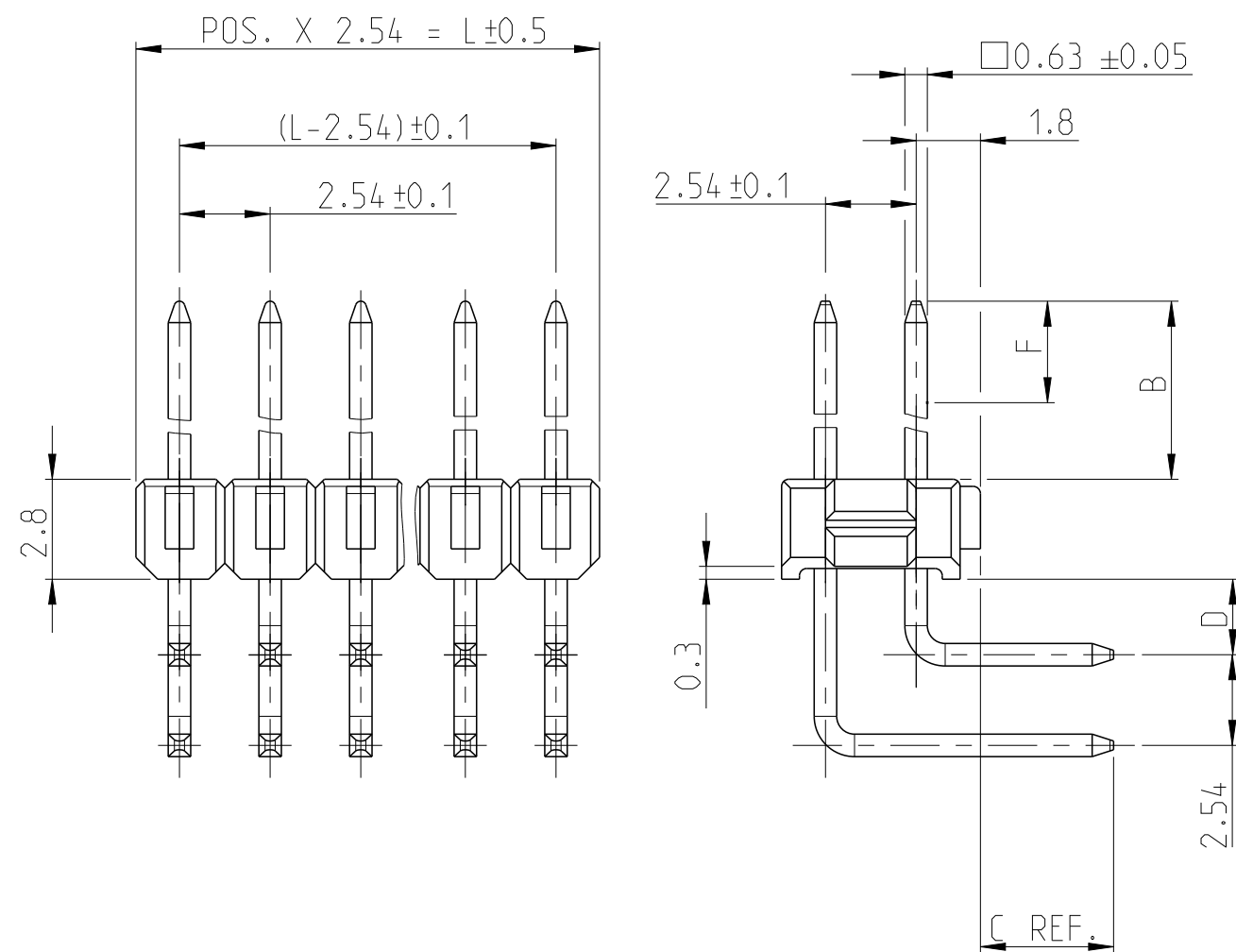
P	LTR	DESCRIPTION	DATE	DWN	APVD
		SEE SHEET 1			

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REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
		SEE SHEET 1			

D



“F” = GOLD AREA

DIMENSION						PART-NO.		PART- NO.		PART- NO.	
						SELECTIVE GOLD PLATED		TIN PLATED		SELECTIVE GOLD PLATED	
B	C	D	F	-			WEIGHT POS. PER ROW		WEIGHT POS. PER ROW		WEIGHT POS. PER ROW
6.7	3.2	1.3	4.4	-		826634	0.1646 g	826953	0.1656 g	828418	0.1651 g
6.7	2.5	1.3	4.4	-		826661	0.1597 g	826954	0.1606 g		
5.8	3.2	1.3	4.4	-		826662	0.1587 g	826955	0.1603 g	829072	0.1587 g
5.8	2.5	1.3	4.4	-		826663	0.1538 g	826956	0.1542 g		
8.0	3.2	1.3	4.4	-		826664	0.1741 g	826957	0.1749 g		
8.0	2.5	1.3	4.4	-		826665	0.1687 g	826958	0.1699 g		

CONTACT PIN	CuZn	SEE TABLE
PIN HOUSING	PBT GV	SEE TABLE
DESCRIPTION	MATERIAL	FABRE/COLOR/PLATING/SURFACE

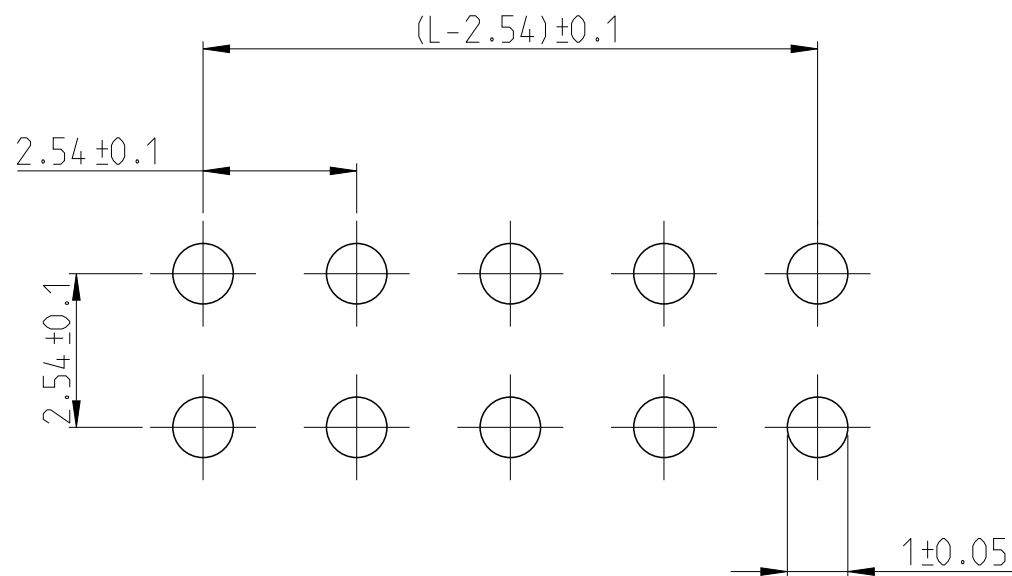
NOTES:

- MATING SIDE : AREA “F” MIN 0.76µm (PdNi + Au FLASH) (Alternative plating - Min 0.76µm Au plating) OVER 1.27µm NICKEL BY AREA “B”
SOLDER SIDE: MIN 3µm TIN OVER 1.27µm NICKEL
- MATING AND SOLDER SIDE : MIN 3µm TIN OVER 1.27µm NICKEL
- MATING SIDE: AREA “F” 0.13µm GOLD OVER 1.27µm NICKEL BY AREA “B”
SOLDER SIDE: MIN 3µm TIN OVER 1.27µm NICKEL
- COLOR OF HOUSING: GREY
- COLOR OF HOUSING: GREEN
- TOLERANCES NOT CUMULATIVE
- THE NUMBER OF POSITION PER ROW HAS TO BE ADDED TO THE BASE NO. AS A DASH NO.
EG: 2-826634-0 = 20 POSITIONS

THE NUMBER OF POSITIONS PER ROW IS ALSO THE FACTOR FOR THE WEIGHT DETERMINATION
E.G: 20 X 0.1646 g = 3.292 g
- OBSOLETE

C

B



SCALE 8:1
LAYOUT FOR HOLES ON PCB

A

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:

mm

MATERIAL

SEE TABLE

-

TOLERANCES UNLESS OTHERWISE SPECIFIED:

±0.2mm

0 PLC ±
1 PLC ±
2 PLC ±
3 PLC ±
4 PLC ±
ANGLES ±
FINISH -
-

DWN

G.HOLAUS

10NOV1989

CHK

SCHAARSCHMIDT M.

APVD

PRODUCT SPEC

108-18012

APPLICATION SPEC

114-25011

WEIGHT

-

CUSTOMER DRAWING

TE Connectivity

NAME

AMPMODU II PIN HEADER,
SINGLE ROW, DUAL ROW,
VERTICAL AND RIGHT ANGLE MOUNT

SIZE

A2

CAGE CODE

00779

DRAWING NO

C-826629

RESTRICTED TO

-

SCALE

5:1

SHEET

4

OF

4

REV

AC 2

D

C

B

A

Mouser Electronics

Authorized Distributor

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